

ESD7008

Transient Voltage Suppressors

Low Capacitance ESD Protection for High Speed Data

The ESD7008 transient voltage suppressor is designed specifically to protect four high speed differential pairs. Ultra-low capacitance and low ESD clamping voltage make this device an ideal solution for protecting voltage sensitive high speed data lines. The flow-through style package allows for easy PCB layout and matched trace lengths necessary to maintain consistent impedance for the high speed lines.

Features

- Integrated 4 Pairs (8 Lines) High Speed Data
- Single Connect, Flow through Routing
- Low Capacitance (0.12 pF Typical, I/O to GND)
- Protection for the Following IEC Standards:
IEC 61000-4-2 Level 4
- UL Flammability Rating of 94 V-0
- This is a Pb-Free Device

Typical Applications

- V-by-One HS
- Thunderbolt (Light Peak)
- USB 3.0
- HDMI
- Display Port
- LVDS

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Operating Junction Temperature Range	T_J	-55 to +125	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$
Lead Solder Temperature – Maximum (10 Seconds)	T_L	260	$^\circ\text{C}$
IEC 61000-4-2 Contact (ESD)	ESD	± 15	kV
IEC 61000-4-2 Air (ESD)	ESD	± 15	kV

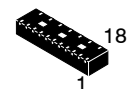
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

See Application Note AND8308/D for further description of survivability specs.



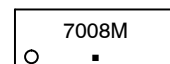
ON Semiconductor®

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UDFN18
CASE 517BV

MARKING DIAGRAM



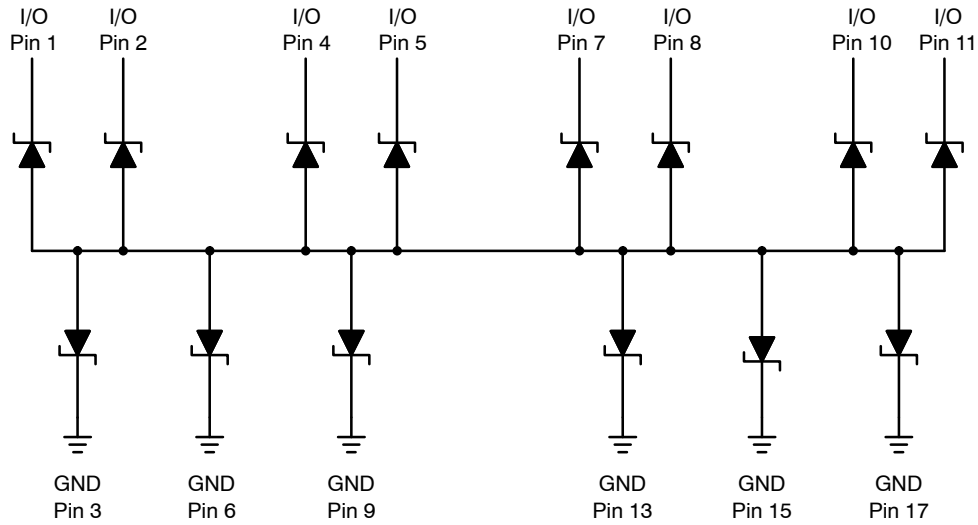
7008 = Specific Device Code
M = Date Code
▪ = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
ESD7008MUTAG	UDFN18 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ESD7008



Note: Only Minimum of 1 GND connection required

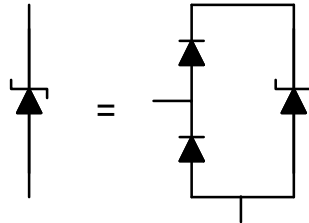


Figure 1. Pin Schematic

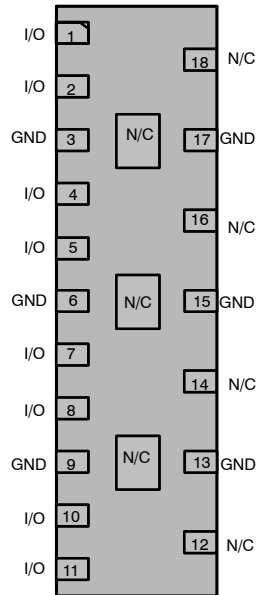


Figure 2. Pin Configuration

Note: Only minimum of one pin needs to be connected to ground for functionality of all pins. All pins labeled "N/C" should have no electrical connection.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse Working Voltage	V _{RWM}	I/O Pin to GND (Note 1)			5.0	V
Breakdown Voltage	V _{BR}	I _T = 1 mA, I/O Pin to GND	5.5			V
Reverse Leakage Current	I _R	V _{RWM} = 5 V, I/O Pin to GND			1.0	μA
Clamping Voltage (Note 1)	V _C	I _{PP} = 1 A, I/O Pin to GND (8 x 20 μs pulse)			10	V
Clamping Voltage (Note 2)	V _C	IEC61000-4-2, ±8 kV Contact	See Figures 3 and 4			V
Clamping Voltage TLP (Note 3) See Figures 8 through 11	V _C	I _{PP} = ±8 A I _{PP} = ±16 A		13.2 18.2		
Junction Capacitance	C _J	V _R = 0 V, f = 1 MHz between I/O Pins and GND		0.12	0.15	pF
Junction Capacitance Difference	ΔC _J	V _R = 0 V, f = 1 MHz between I/O Pins and GND		0.02		pF

1. Surge current waveform per Figure 7.
2. For test procedure see Figures 5 and 6 and application note AND8307/D.
3. ANSI/ESD STM5.5.1 – Electrostatic Discharge Sensitivity Testing using Transmission Line Pulse (TLP) Model.
TLP conditions: Z₀ = 50 Ω, t_p = 100 ns, t_r = 4 ns, averaging window; t₁ = 30 ns to t₂ = 60 ns.

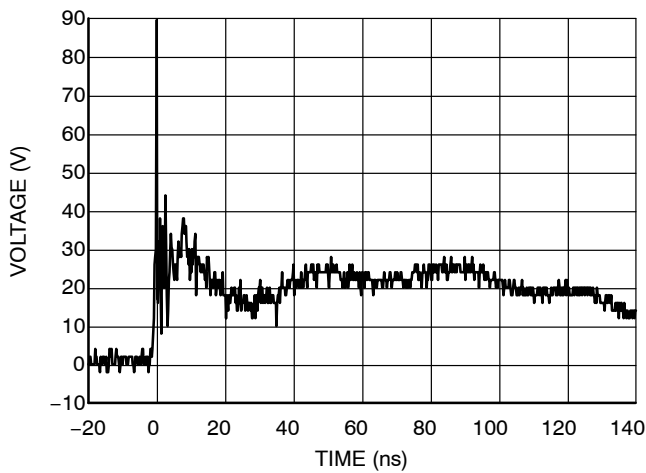


Figure 3. IEC61000-4-2 +8 KV Contact
Clamping Voltage

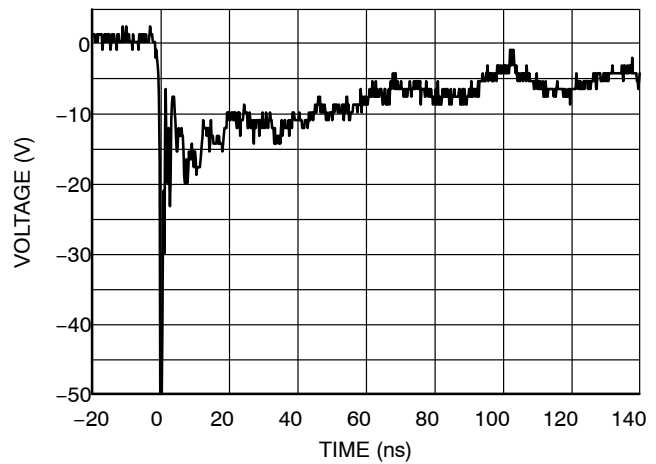


Figure 4. IEC61000-4-2 -8 KV Contact
Clamping Voltage

IEC 61000-4-2 Spec.

Level	Test Voltage (kV)	First Peak Current (A)	Current at 30 ns (A)	Current at 60 ns (A)
1	2	7.5	4	2
2	4	15	8	4
3	6	22.5	12	6
4	8	30	16	8

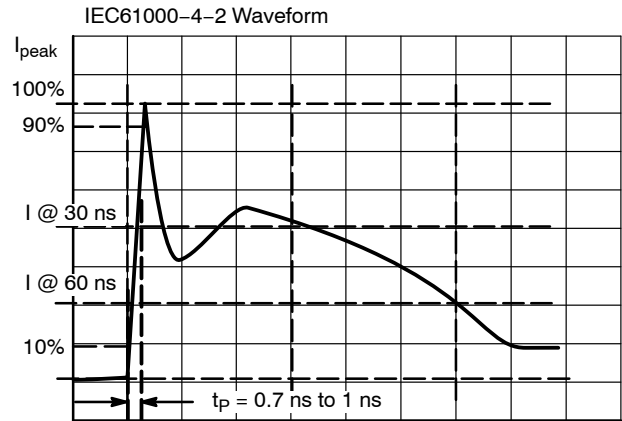


Figure 5. IEC61000-4-2 Spec

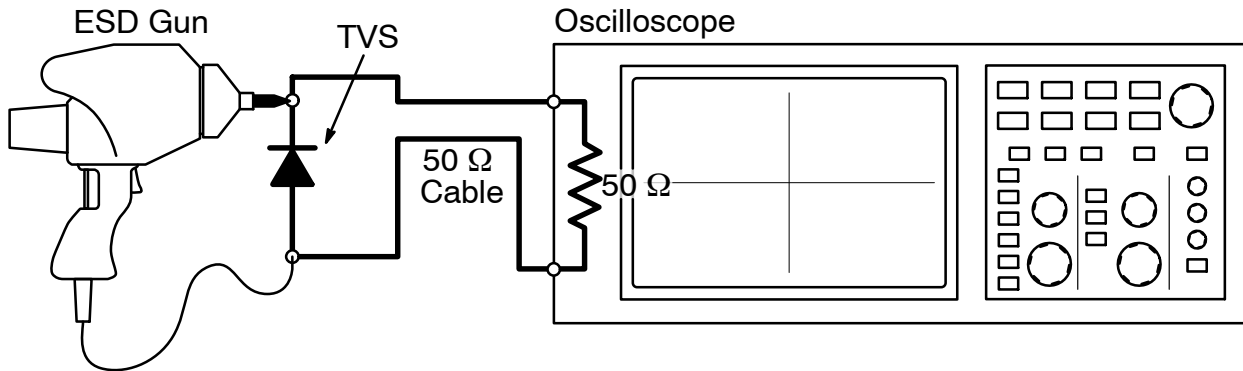


Figure 6. Diagram of ESD Clamping Voltage Test Setup

The following is taken from Application Note
AND8308/D – Interpretation of Datasheet Parameters
for ESD Devices.

ESD Voltage Clamping

For sensitive circuit elements it is important to limit the voltage that an IC will be exposed to during an ESD event to as low a voltage as possible. The ESD clamping voltage is the voltage drop across the ESD protection diode during an ESD event per the IEC61000-4-2 waveform. Since the IEC61000-4-2 was written as a pass/fail spec for larger

systems such as cell phones or laptop computers it is not clearly defined in the spec how to specify a clamping voltage at the device level. ON Semiconductor has developed a way to examine the entire voltage waveform across the ESD protection diode over the time domain of an ESD pulse in the form of an oscilloscope screenshot, which can be found on the datasheets for all ESD protection diodes. For more information on how ON Semiconductor creates these screenshots and how to interpret them please refer to AND8307/D.

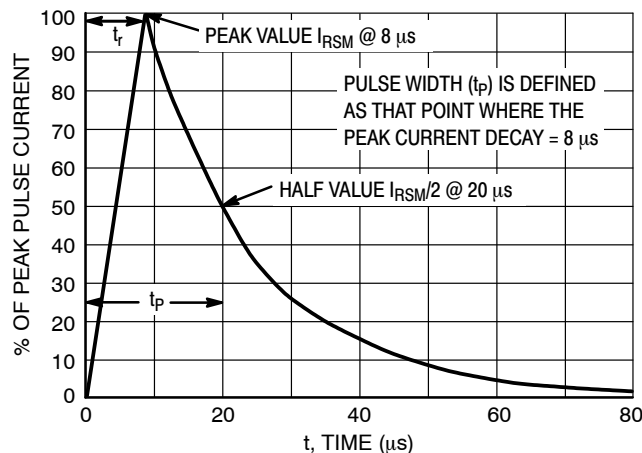


Figure 7. 8 X 20 μ s Pulse Waveform

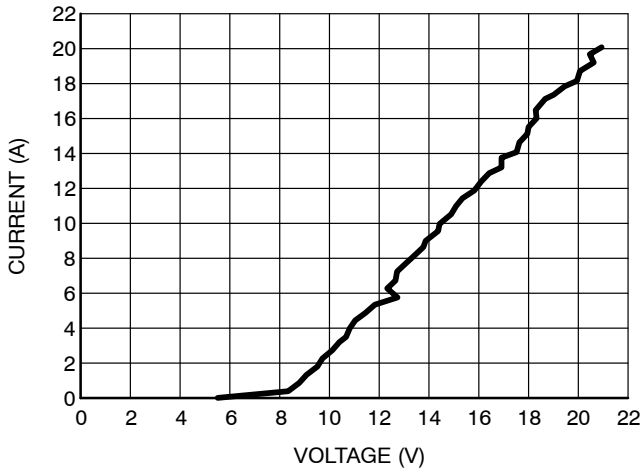


Figure 8. Positive TLP I-V Curve

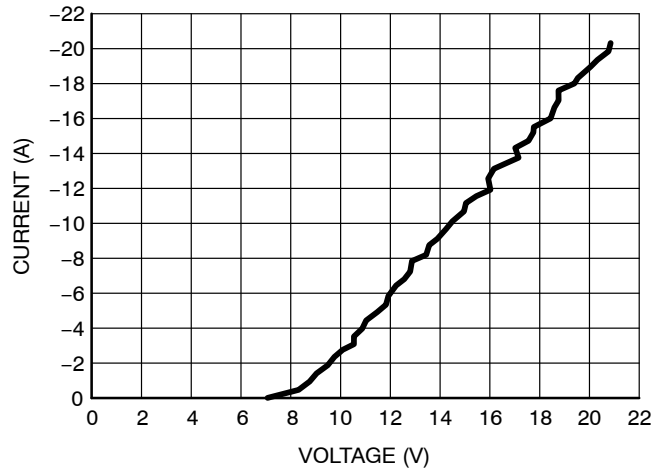


Figure 9. Negative TLP I-V Curve

Transmission Line Pulse (TLP) Measurement

Transmission Line Pulse (TLP) provides current versus voltage (I-V) curves in which each data point is obtained from a 100 ns long rectangular pulse from a charged transmission line. A simplified schematic of a typical TLP system is shown in Figure 10. TLP I-V curves of ESD protection devices accurately demonstrate the product's ESD capability because the 10s of amps current levels and under 100 ns time scale match those of an ESD event. This is illustrated in Figure 11 where an 8 kV IEC 61000-4-2 current waveform is compared with TLP current pulses at 8 A and 16 A. A TLP I-V curve shows the voltage at which the device turns on as well as how well the device clamps voltage over a range of current levels.

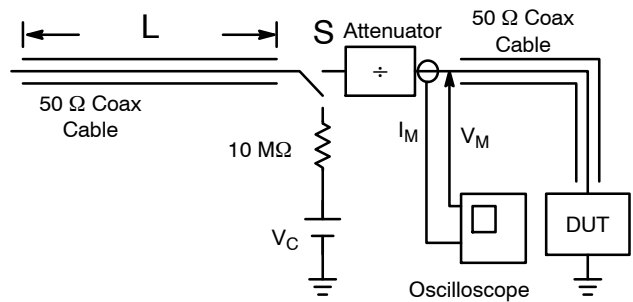


Figure 10. Simplified Schematic of a Typical TLP System

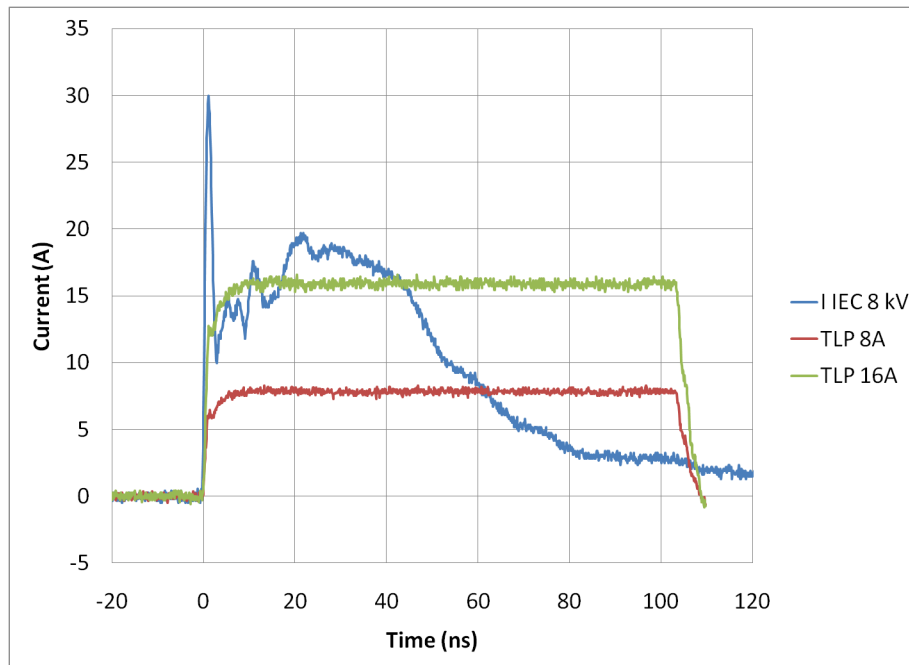


Figure 11. Comparison Between 8 kV IEC 61000-4-2 and 8 A and 16 A TLP Waveforms

ESD7008

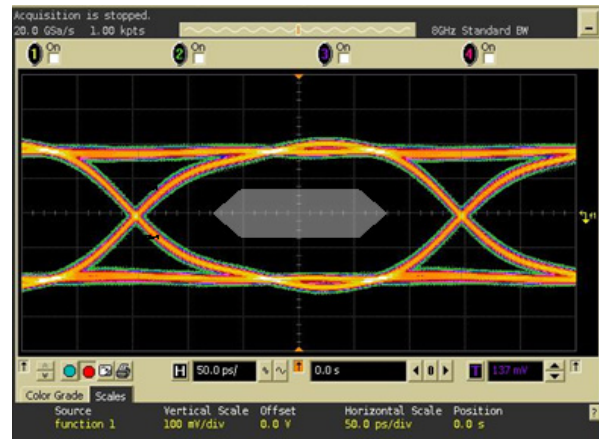
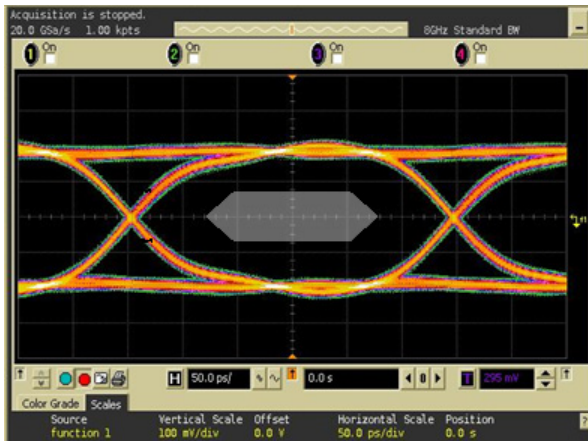


Figure 12. HDMI1.4 Eye Diagram with and without ESD7008. 3.4 Gb/s, 400 mV_{pp}

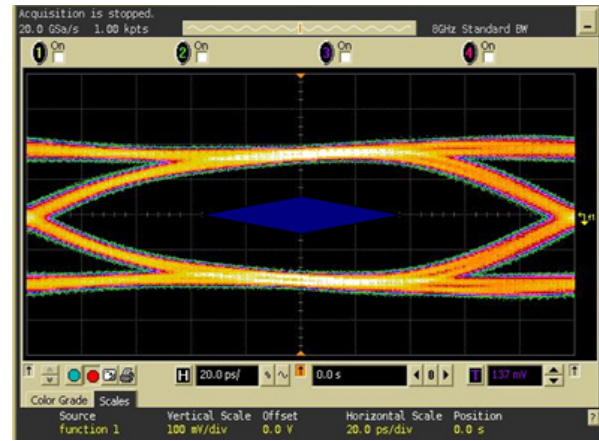
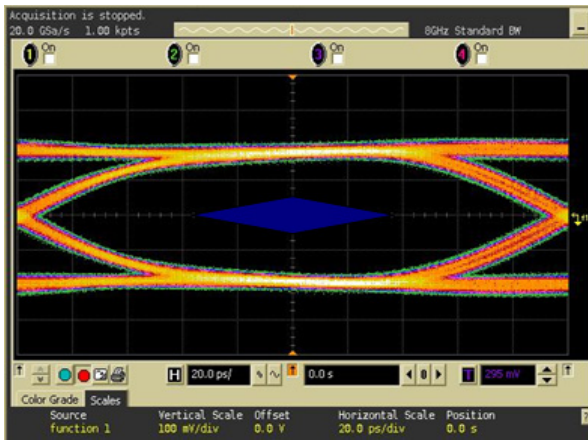


Figure 13. USB3.0 Eye Diagram with and without ESD7008. 5.0 Gb/s, 400 mV_{pp}

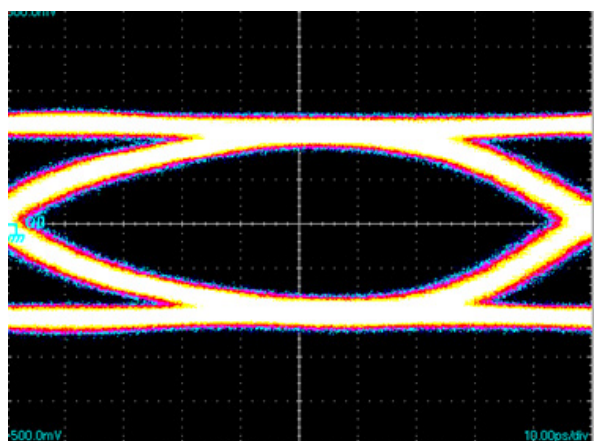
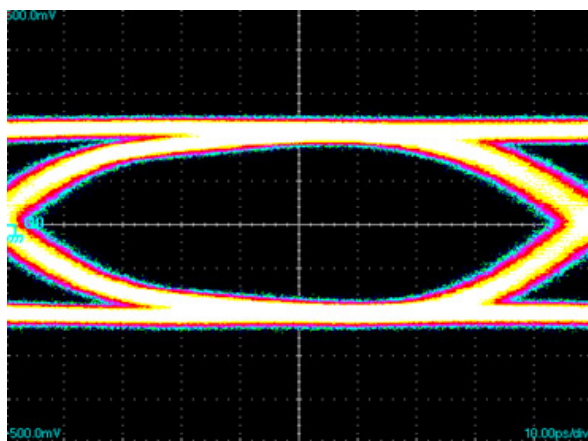


Figure 14. Thunderbolt Eye Diagram with and without ESD7008. 10 Gb/s, 400 mV_{pp}

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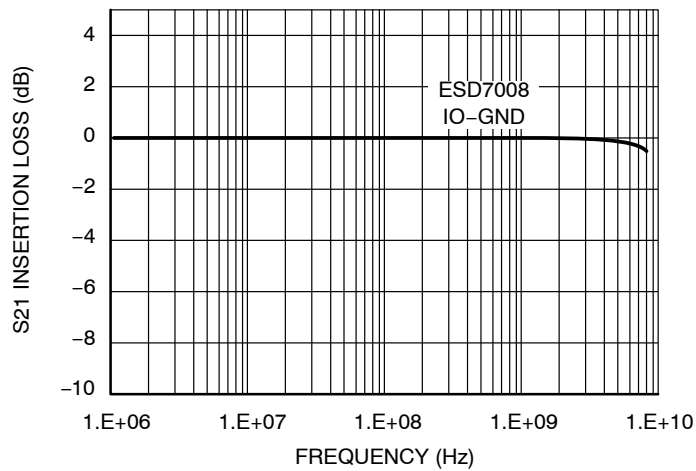


Figure 15. ESD7008 Insertion Loss

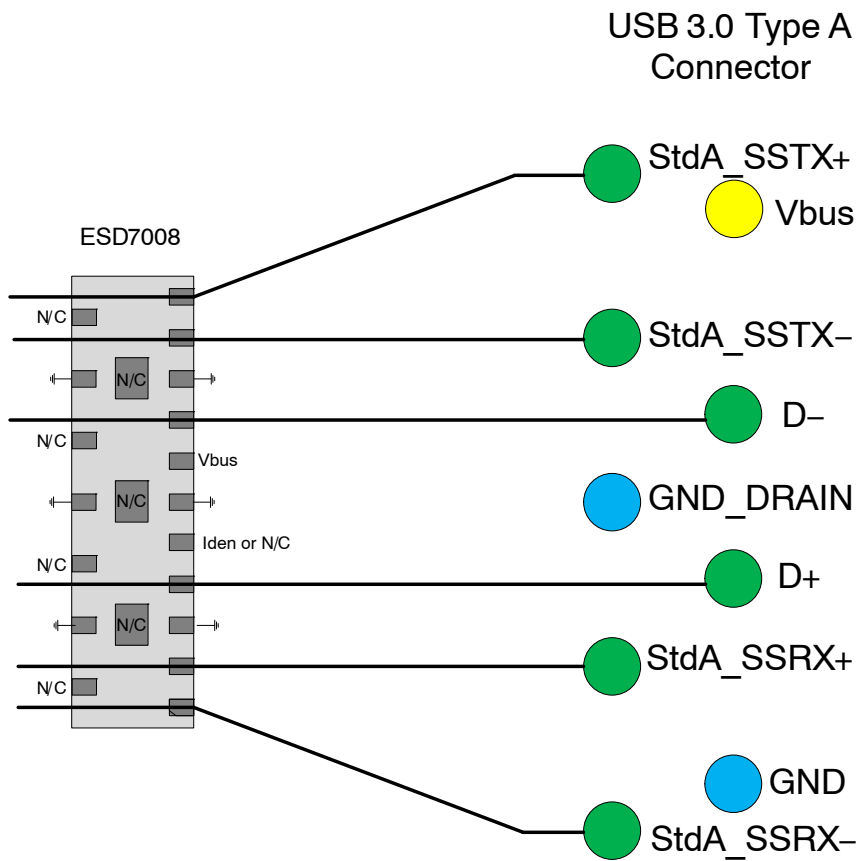


Figure 16. USB3.0 Layout Diagram

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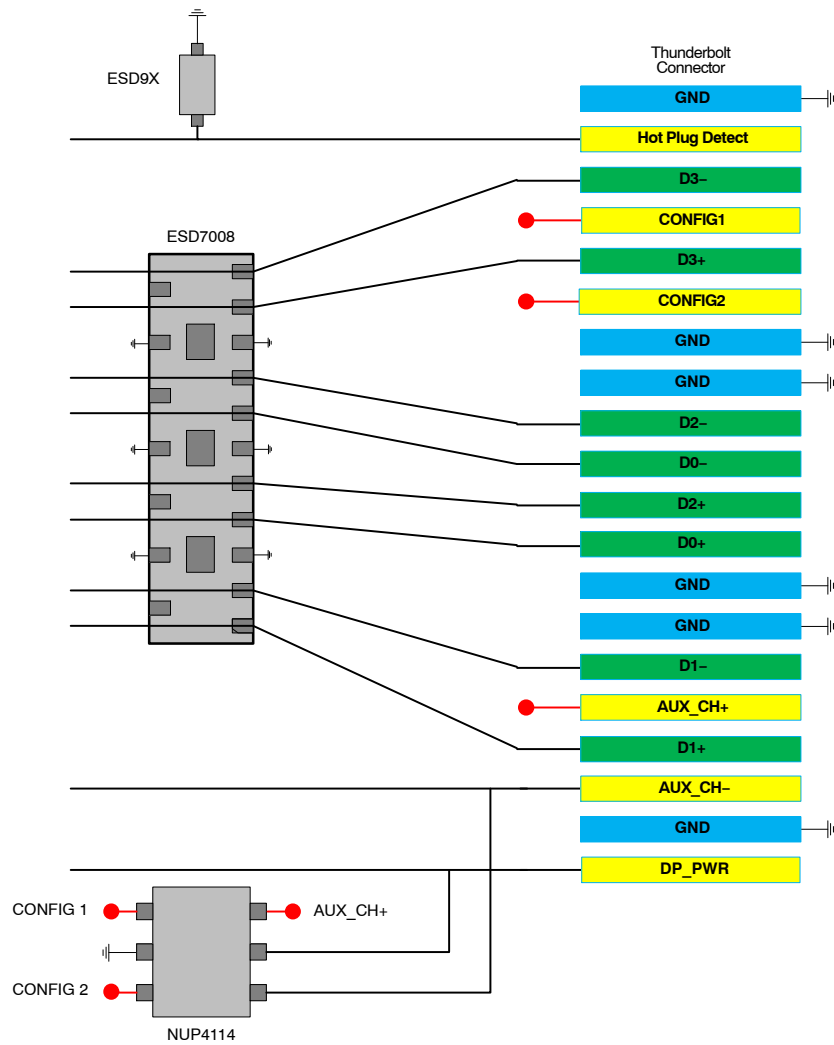


Figure 17. Thunderbolt Layout Diagram

ESD7008

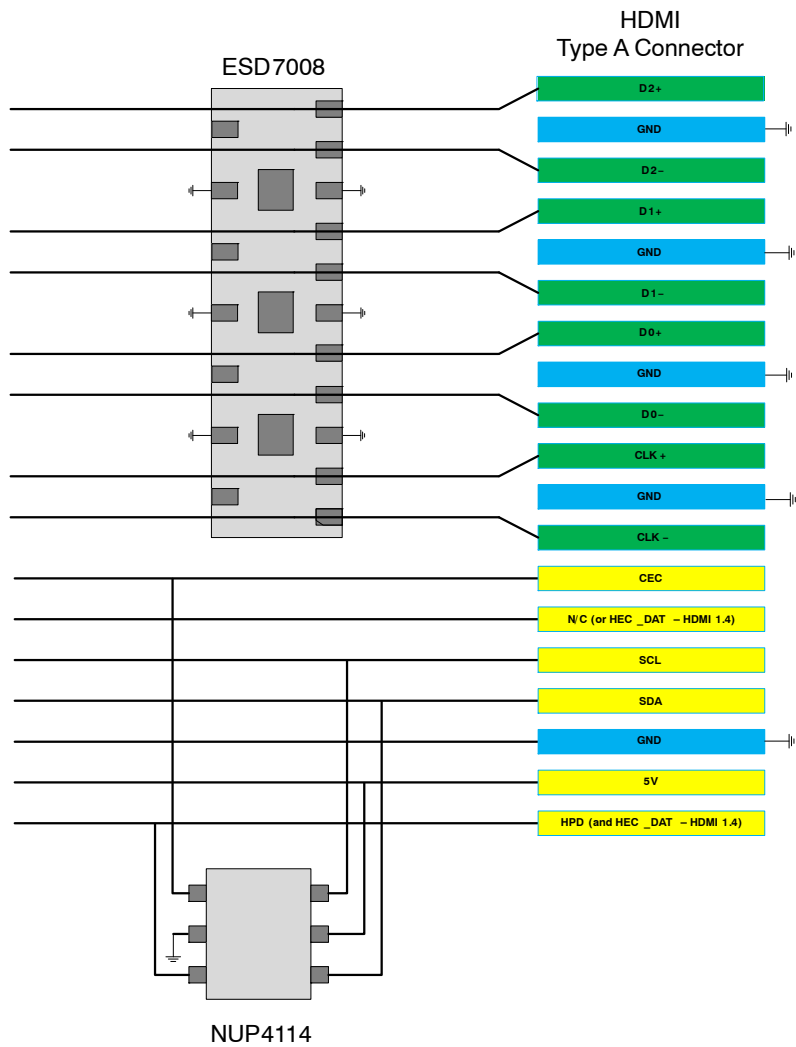


Figure 18. HDMI Layout Diagram

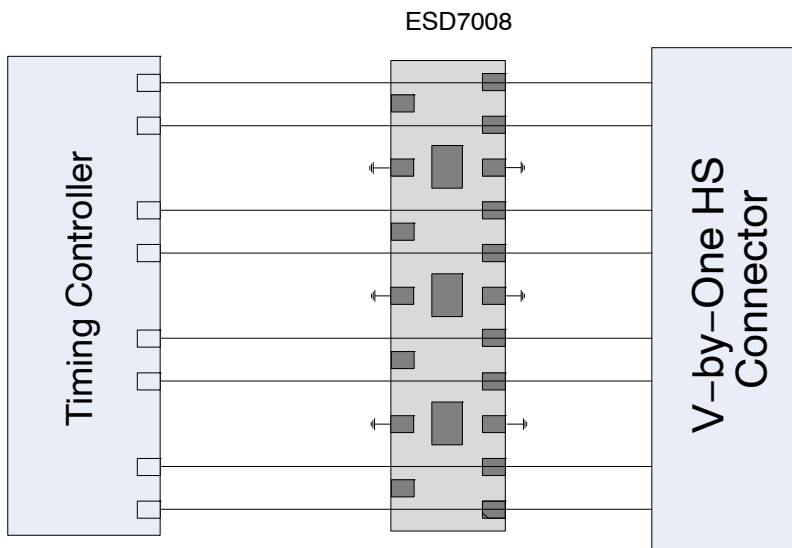
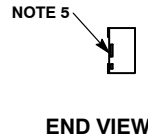
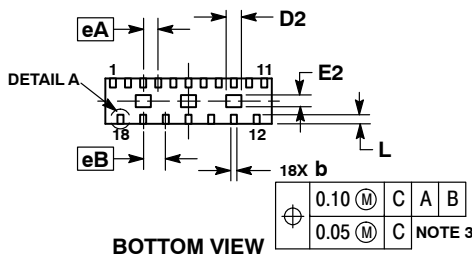
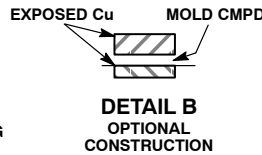
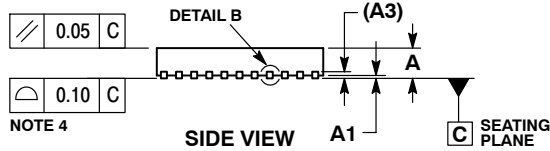
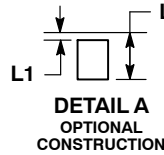
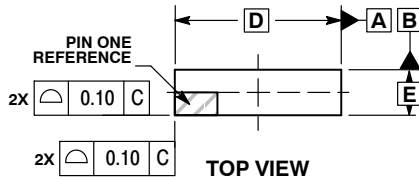


Figure 19. V-by-One HS Layout Diagram (for LCD Panel)

ESD7008

PACKAGE DIMENSIONS

UDFN18, 5.5x1.5, 0.5P CASE 517BV ISSUE O

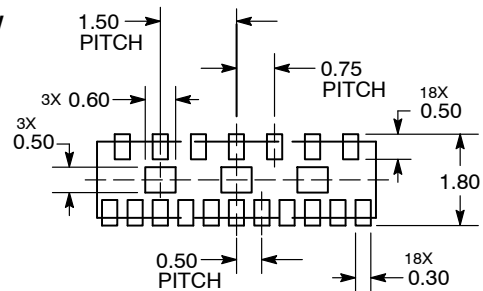


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.20 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. EXPOSED ENDS OF TERMINALS ARE ELECTRICALLY ACTIVE.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.15	0.25
D	5.50	BSC
D2	0.45	0.55
E	1.50	BSC
E2	0.35	0.45
eA	0.50	BSC
eB	0.75	BSC
L	0.20	0.40
L1	0.00	0.05

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSION: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

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